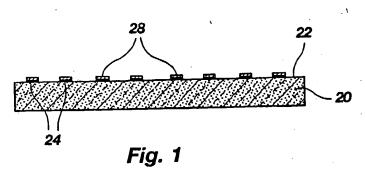
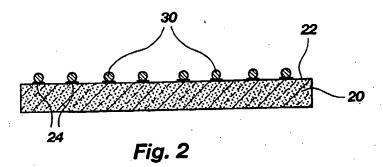
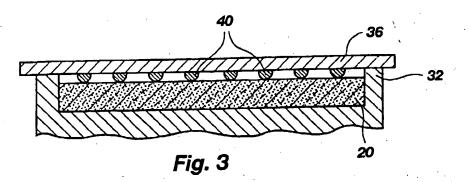
APPROVEL	O.G. FIG.		
BY	CLASS	SUBCLASS	
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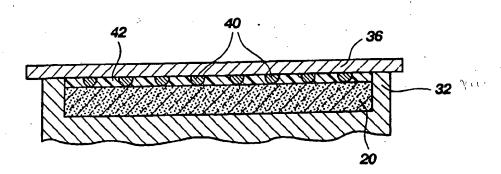
TITLE: METHOD OF FORMING OVERMOLDED CHIP SCALE PACKAGE AND RESULTING PRODUCT Inventor: Warren M. Farnworth Serial No.: Not Yet Assigned Docket No.: 3085.4US

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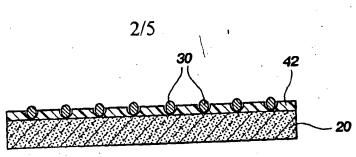


Fig. 5

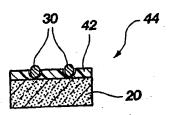


Fig. 6

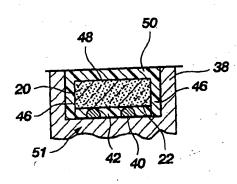


Fig. 7

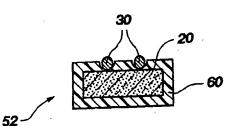
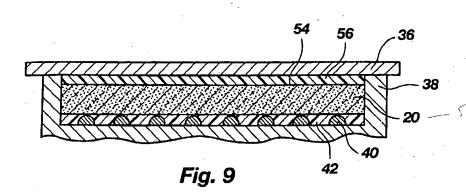


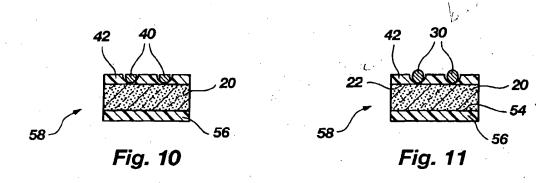
Fig. 8

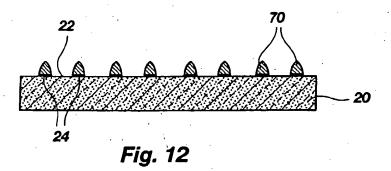
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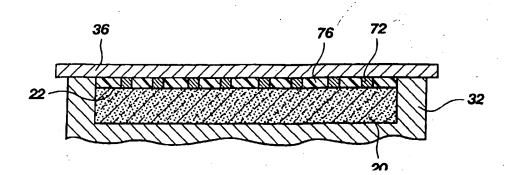
TITLE: METHOD OF FORMING OVERMOLDED CHIP SCALE
PACKAGE AND RESULTING PRODUCT
Inventor: Warren M. Farnworth
Serial No.: Not Yet Assigned
Docket No.: 3085.4US











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PACKAGE AND RESULTING PRODUCT
Inventor: Warren M. Farnworth
Serial No.: Not Yet Assigned
Docket No.: 3085.4US

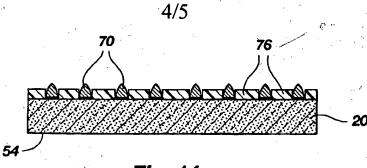


Fig. 14

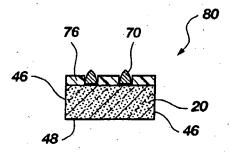


Fig. 15

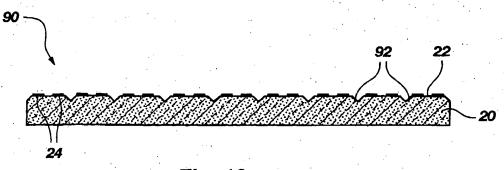


Fig. 16

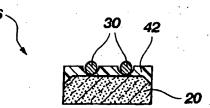


Fig. 17

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RY	CLASS	SUBCLASS
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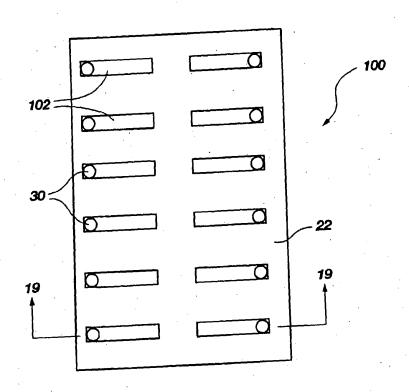


Fig. 18

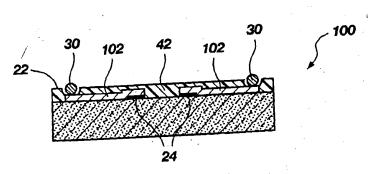


Fig. 19